

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): Won Sun Shin et al.

Assignee: Amkor Technology, Inc.

Title: SEMICONDUCTOR PACKAGE AND METHOD FOR FABRICATING  
THE SAME

Serial No.: 10/600,931 Filed: June 20, 2003

Examiner: Nguyen, Cuong Group Art 2811  
Quang Unit:

Docket No.: GK001501

Monterey, CA  
September 28, 2004

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Dear Sir:

In response to the Office Action dated September 2, 2004,  
please amend the above-identified application as follows:

1. **Amendments to the Specification** begin on page 2  
of this paper;
2. **Amendments to the Claims** are reflected in the  
listing of Claims which begins on page 3 of this paper;  
and
3. **Remarks** begin on page 8 of this paper.